

Specification

(Reference)

Title: FIXED THICK FILM CHIP RESISTORS;
RECTANGULAR TYPE AND ULTRAHIGH VOLTAGE

Style: RZC50, 63

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Halogen and Antimony Free

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KAMAYA ELECTRIC CO., LTD.

Issue Dept.: Research & Development Department Hokkaido Research Center

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND
ULTRAHIGH VOLTAGE RZC50, 63

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1. Scope

1.1 This specification covers the detail requirements for fixed thick film chip resistors; rectangular type and ultrahigh voltage, style of RZC50, 63.

1.2 Applicable documents

JIS C 5201-1: 1998, JIS C 5201-8: 1998, JIS C 5201-8-1: 1998

IEC60115-1: 1999, IEC60115-8: 1989 Amendment 1: 1992, IEC60115-8-1: 1989

EIAJ RC-2134B-2002

2. Classification

Type designation shall be the following form.

(Example)

RZC	63	-	475	J	TE
1	2	3	4	5	6

Style

- 1 Fixed thick film chip resistors; rectangular type & precision Style
- 2 Rated dissipation and / or dimension
- 3 Temperature coefficient of resistance
- 4 Rated resistance Example; 475 → 4.7MΩ
- 5 Tolerance on rated resistance
- 6 Packaging form

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Rated dissipation (W)	Temperature coefficient of resistance (10 ⁻⁶ / °C)		Rated resistance range (Ω)	Preferred number Series for resistors	Tolerance on rated resistance
RZC50	0.5	Standard	±200	1M~16M	E24	J(±5%), K(±10%), M(±20%)
RZC63	1.0					

Style	Limiting element voltage (V)	Isolation voltage (V)	Category temperature range (°C)
RZC50	1500	500	-55~+125
RZC63	2000		

3.2 Climatic category

55/125/56

Lower category temperature - 55 °C
Upper category temperature +125 °C
Duration of the damp heat, steady state test 56days

3.3 Stability class

5%

Limits for change of resistance:

-for long-term tests ±(5%+0.1Ω)
-for short-term tests ±(1%+0.05Ω)

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

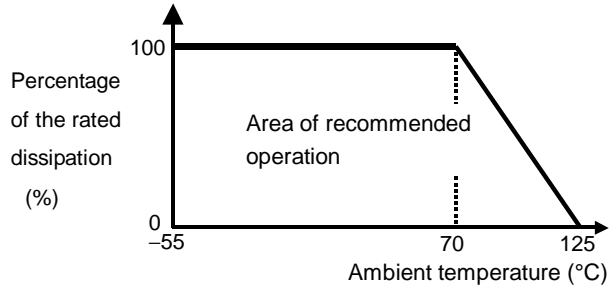


Figure-1 Derating curve

3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E : Rated voltage (V)

P : Rated dissipation (W)

R : Rated resistance (Ω)

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units
B	Bulk (loose package)		1,000 pcs.
TE	Embossed taping	12mm width, 4mm pitches	4,000 pcs.

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

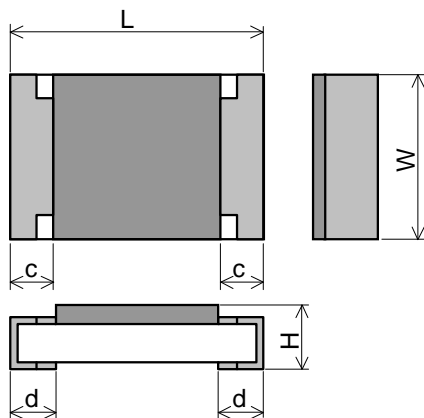


Figure-2

Table-3

Unit : mm

Style	L	W	H	c	d
RZC50	5.0 ± 0.15	2.5 ± 0.15	0.55 ± 0.15	0.6 ± 0.2	0.6 ± 0.2
RZC63	6.3 ± 0.15	3.2 ± 0.15	0.55 ± 0.15	0.6 ± 0.2	0.6 ± 0.2

5.2 Net weight (Reference)

Style	Net weight(mg)
RZC50	25
RZC63	40

6. Marking

The Rated resistance shall be marked in 3 digits (E24) and marked on over coat side.

(Example) "475" $\rightarrow 47 \times 10^5 [\Omega] \rightarrow 4.7 [M\Omega]$

7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201-1: 1998.

7.2 The performance shall be satisfied in Table-4.

Table 4(1)

[illegible]

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Table-4(2)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
6	Mounting Bound strength of the end face plating Final measurements	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-4 Sub-clause 4.33 Bent value: 1 mm Resistance Sub-clause 4.33.6 Visual examination	$\Delta R \leq \pm (1\%+0.05\Omega)$ No visible damage
7	Resistance to soldering heat Component resistance solvent	Sub-clause 4.18 Solvent temperature: $260\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$ Immersion time: $5\text{ s} \pm 0.5\text{ s}$ Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: $23\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$ Method 2 Recovery: 48 h Visual examination Resistance	As in 4.18.3.4 No sign of damage such as cracks. $\Delta R \leq \pm (1\%+0.05\Omega)$ No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$
8	Mounting Adhesion Rapid change temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.32 Force: 5 N Duration: $10\text{ s} \pm 1\text{ s}$ Visual examination Sub-clause 4.19 Lower category temperature: $-55\text{ }^{\circ}\text{C}$ Upper category temperature: $+125\text{ }^{\circ}\text{C}$ Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$

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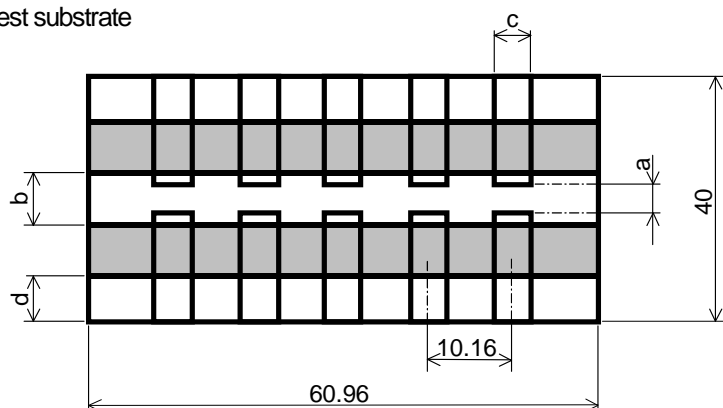
Table-4(3)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
9	Climatic sequence –Dry heat –Damp heat, cycle (12+12hour cycle) First cycle –Cold –Damp heat, cycle (12+12hour cycle) Remaining cycle –D.C. load	Sub-clause 4.23 Sub-clause 4.23.2 Test temperature: +125 °C Duration: 16 h Sub-clause 4.23.3 Test method: 2 Test temperature: 55 °C [Severity(2)] Sub-clause 4.23.4 Test temperature –55 °C Duration: 2h Sub-clause 4.23.6 Test method: 2 Test temperature: 55 °C [Severity (2)] Number of cycles: 5 cycles Sub-clause 4.23.7 The applied voltage shall be the rated voltage or the limiting element voltage which ever is the smaller. Duration: 1 min. Visual examination Resistance	No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$
10	Mounting Endurance at 70 °C	Sub-clause 4.31 Substrate material: Epoxide woven glass (RZC63 may use Alumina substrate.) Test substrate: Figure-3 Sub-clause 4.25.1 Ambient temperature: 70 °C \pm 2 °C Duration: 1000 h The voltage shall be applied in cycles of 1.5 h on and 0.5 h. The applied voltage shall be the rated voltage or the limiting element voltage which ever is the smaller. Examination at 48 h , 500 h and 1000 h: Visual examination Resistance	No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$
11	Mounting Variation of resistance with temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.8 –55 °C / +20 °C +20 °C / +125°C	As in Table-1

Table-4(4)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
12	Mounting Damp heat, steady state	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.24 Ambient temperature: 40 °C ± 2 °C Relative humidity : 93 \pm ₃ % a) 1st group: without voltage applied. b) 2nd group: The d. c. voltage shall be applied continuously. The voltage shall be accordance with Sub-clause 4.24.2.1 b). without polarizing voltage [4.24.2.1, c)] Visual examination Resistance	No visible damage Legible marking $\Delta R \leq \pm (5\%+0.1\Omega)$
13	Dimensions (detail) Mounting Endurance at upper category temperature	Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.25.3 Ambient temperature:125 °C ± 2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	As in Table-3 No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$
14	Mounting Anti-rush voltage test	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Ambient temperature:25°C ± 2 °C The voltage shall be applied in cycles of 1 s "ON", 9 s "OFF". Test voltage: 3000V Visual examination Resistance	No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$

8. Test substrate



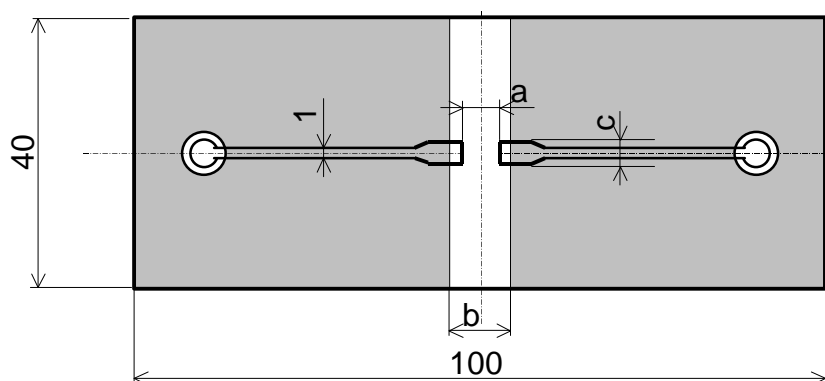
Unit: mm

□ :Copper clad
■ :Solder resist

Style	a	b	c	d
RZC50	4.0	7.5	2.0	7.5
RZC63	5.0	9.0	4.5	7.5

Figure-3 RZC50, 63 TEST SUBSTRATE

- Remark 1). Material: Epoxide woven glass
Thickness: 1.6mm Thickness of copper clad: 0.035mm
- 2). In the case of connection by connector, the connecting terminals are gold plated.
However, the plating is not necessary when the connection is made by soldering.



Unit: mm

□ :Copper clad
■ :Solder resist

Style	a	b	c
RZC50	4.0	7.5	3.0
RZC63	5.0	9.0	4.0

Figure-4 RZC50, 63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

- Remark 1). Material: Epoxide woven glass
Thickness: 1.6mm Thickness of copper clad: 0.035mm

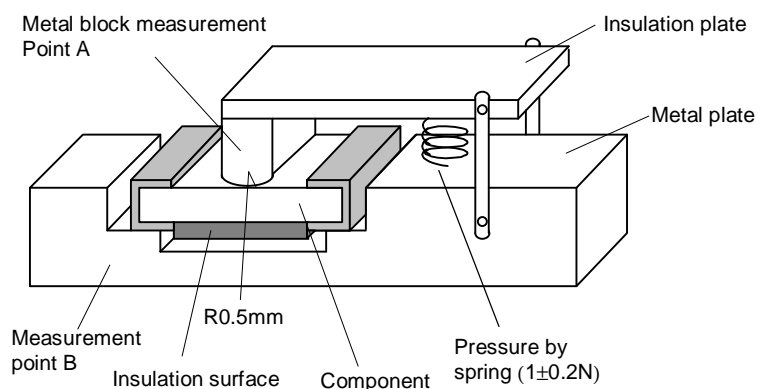


Figure-5

9. Taping

9.1 Applicable documents JIS C 0806-3: 1999, EIAJ ET-7200B: 2003

9.2 Taping dimensions

Embossed taping dimensions shall be in accordance with Figure-6 and Table-5.

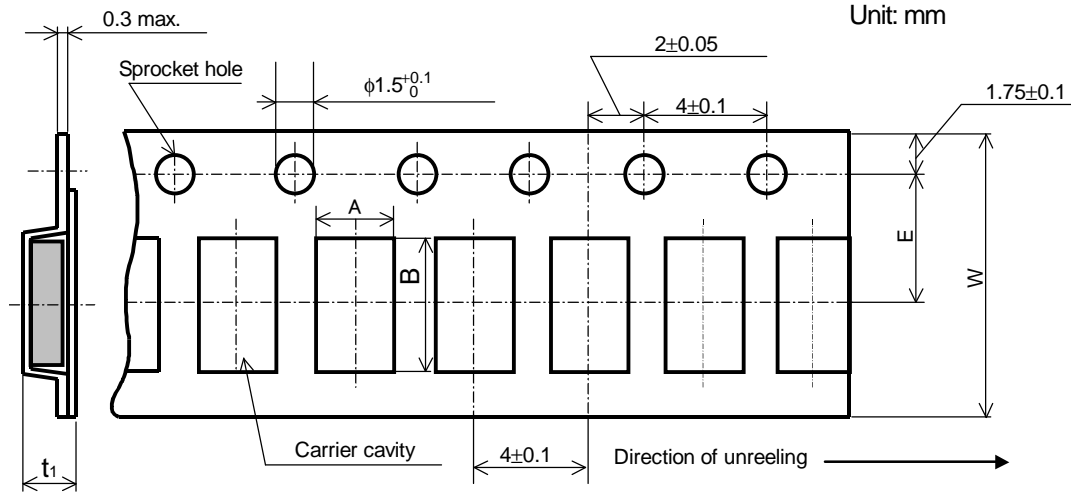


Figure-6

Table-5

Unit: mm

Style	A	B	W	E	t ₁
RZC50	3.1±0.2	5.5±0.2	12.0±0.3	5.5±0.05	1.1±0.15
RZC63	3.6±0.2	6.9±0.2			

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches $\pm 0.2\text{mm}$.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure-7.
- 6). When the tape is bent with the minimum radius for 30 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.

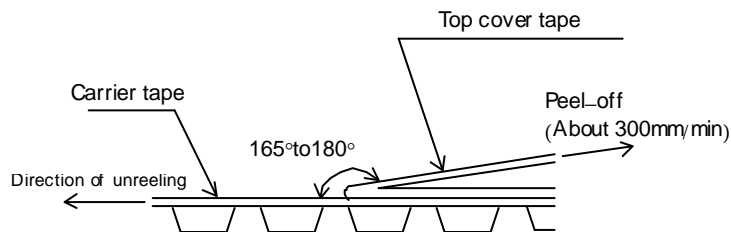


Figure-7

9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-8 and Table-6.

Plastic reel (Based on EIAJ ET-7200B)

Unit: mm

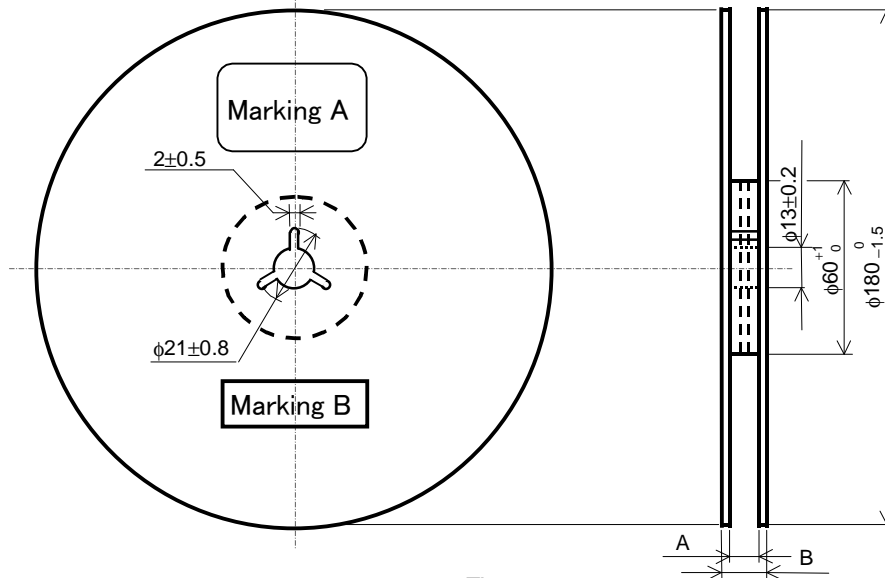


Figure-8

Table-6

Unit: mm

Style	A	B	Note
RZC50,63	13 $^{+1.0}_0$	17 ± 1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

9.4 Leader and trailer tape.

(Example)

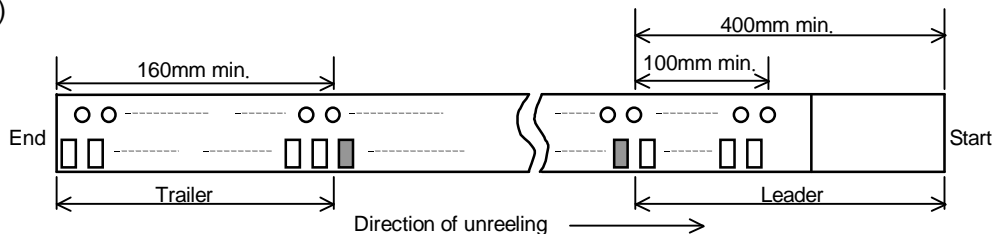


Figure-9

10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

- (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Packaging form)
- (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others

10.2 Marking B (KAMAYA Control label)

Mouser Electronics

Authorized Distributor

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Kamaya:

[RZC63-105JTE](#) [RZC50-156JTE](#) [RZC50 106K TE](#)



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